

IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Approval

Independent Testing Laboratory

IECQ Certificate No.: IECQ-L NSAIUS 08.0002
CB Certificate No.: 1.72.0031

Schedule Number: IECQ-L NSAIUS 08.0002-S Rev No.: 9 Revision Date: 2014-08-26 Page 1 of 1

Issue to: Integrated Service Technology, Inc. 1F No. 19 Pu-Ding Road Hsin-Chu City 300 Taiwan, R.O.C.

Process or service in respect of which the company is Certified:

- 1 Environmental and reliability testing (JEDEC, AEC-Q100/Q101/Q200 , IEC 60529, IEC 60068-2 -1 to IEC 60068-2 -64, Mil-STD-810 & Mil-STD-883)
- 2 Failure analysis and material analysis
- 3 2nd Level Integration Platform Service

Scope of Certification:

1. Environmental and reliability testing (JEDEC, AEC-Q100/Q101/Q200 , IEC 60529, IEC 60068-2 -1 to IEC 60068-2 -64, Mil-STD-810 & Mil-STD-883)

Electrostatic discharge test, Low temperature, High temperature test, Humidity storage test, Temperature cycling test, Thermal shock test, Pressure cook test, Highly Accelerated Temperature and Humidity Stress test (JESD22-A110), Low pressure, altitude test, Temperature and Humidity Bias Life test, Temperature, Bias and Operating Life test (JESD22-A108), Rain test, Salt spray test, Mixed flowing gas test, Solar radiation test, Sand and dust test, Preconditioning of Nonhermetic Surface Mount Device Prior To Reliability Testing, Surface Insulation Resistance and Electrochemical Migration, Solderability (wetting Balance) test, Vibration test, Shock test, Free fall test, Acoustic noise test and LED Luminaries test, IC EMC test, Gate Leakage test, Endurance & Data Retention test and Power & Temperature cycling test and Early Life Failure Rate Test (AEC 0100-008).

- 2. **Failure analysis and material analysis** of semiconductor integrated circuits, electronic components and PCB/PCBA, including FIB (Focused Ion Beam), Electrical Analysis, Sample Preparation (Decap, X-section, etc), NDE (Non-destructive Engineering), Physical & Chemical Analysis (Including Hazardous Substances) and IC package.
- 3. **2nd Level Integration Platform Service**, including SMT and 2nd reliability Services (Temperature Cycle (IPC9701) Test, Board Level Drop Test, Shock Test, Vibration Test, Bending Test (Cyclic bend & Monotonic bend (IPC9702)), Pull/Push Test and SMT and PCBA test (Cold ball pull test, wire pull test, ball shear test and hot bond pull test)).

This schedule is only valid in conjunction with the referenced Certificate of Approval
This approval and any schedule(s) may only be reproduced in full.
This approval is not transferable and remains the property of the issuing body.
The Status and authenticity of this approval and any schedule(s) may be verified by visiting the
Official IECQ Website. www.iecq.org